

KB-3152 (ANSI : FR-1/JIS PP7F)

覆銅箔酚醛樹脂紙基層壓板

特點

- 氣味少
- 无鹵板材，有利於環境保護
- 高耐漏電起痕指數（600 伏以上，需提出特殊要求）
- 適合之沖孔溫度為室溫~70℃
- 彎曲率、扭曲率小且穩定

Features

- Less odor
- Halogen-free, Friendly to the environment.
- High CTI value (over 600V, must specify when require)
- Suitable for punching at ambient~70℃
- warping and twist are small and stable.

General Properties 一般特性

| Test Item 測試項目 | Unit 單位 | Test Condition 處理條件 | Testing Method 測試方法 | Specification 規格值 | Typical Value 典型值 |
|--|-----------------------|--|------------------------|---|--|
| Solder Resistance 耐浸焊性(260℃) | Sec | A | JIS C 6481 | ≥10 | 20~35 |
| Heat Resistance 耐熱性 | --- | 130℃ 30min | JIS C 6481 | No Change 無異常 | No Change 無異常 |
| Peel Strength(Copper Foil 35 μm) 銅箔剝離強度(35 μm 銅箔) | Kgf/cm | A 260℃/5Sec | JIS C 6481 | ≥1.2 | 1.7~2.0 1.6~1.9 |
| Flexural Strength 屈曲強度 | Lengthwise 縱向 | A | JIS C 6481 | ≥8 | 15~17 |
| | Crosswise 橫向 | | | ≥8 | 14~15 |
| Volume Resistivity 體積阻抗係數 | Ω-cm | C-96/20/65 C-96/20/65+C-96/40/90 | JIS C 6481 | 1×10 ⁹ 1×10 ⁸ | 1.0×10 ¹² ~10 ¹³ 1×10 ¹⁰ ~10 ¹¹ |
| Surface Resistance 表面抗阻 | Adhesive Side 粘接劑面 | C-96/20/65 C-96/20/65+C-96/40/90 | JIS C 6481 | 1×10 ¹⁰ 1×10 ⁹ | 1.0×10 ¹¹ ~10 ¹² 1.0×10 ¹⁰ ~10 ¹¹ |
| | Laminate Side 積層板面 | C-96/20/65 C-96/20/65+C-96/40/90 | | --- | --- |
| Insulation Resistance 絕緣抗阻 | Ω | C-96/20/65 C-96/20/65+D-2/100 | JIS C 6481 | 1×10 ⁹ 1×10 ⁶ | 1.0×10 ¹¹ ~10 ¹² 1.0×10 ⁸ ~10 ¹⁰ |
| Chemical Resistance 耐化學性 | --- | 3% NaOH 40℃ 3min 3%氫氧化鈉 40℃ 3 分鐘 | JIS C 6481 | No change 無異常 | No Change 無異常 |
| | | Boiled in trichloroethylene for 3 min 三氯乙烷中煮沸 3 分鐘 | JIS C 6481 | No change 無異常 | No Change 無異常 |
| Water Absorption 吸水性 | % | E-24/50+D-24/23 | JIS C 6481 | ≤2 | 0.7~0.9 |
| Flammability 阻燃性 | Sec | A | UL94 | 94V-0 | 94V-0 |
| Dielectric Constant (1 MHz) 介電常數 (1 MHz) | --- | C-96/20/65 C-96/20/65+D-24/23 | JIS C 6481 | ≤5.5 ≤6.0 | 4.0~5.0 4.5~5.5 |
| Dissipation Factor 介質損耗因數 | --- | C-96/20/65 C-96/20/65+D-24/23 | JIS C 6481 | ≤0.05 ≤0.1 | 0.025~0.035 0.035~0.045 |
| CTI Value CIT 值 | V | 0.1% NH ₄ Cl | IEC 112 | --- | 200 / 600 |
| Punching Temperature 沖孔溫度 | ℃ | A | WI-QA-002 | 40~60 | Ambient~70 |

Remarks: Typical values for reference only 注：典型值只作參考

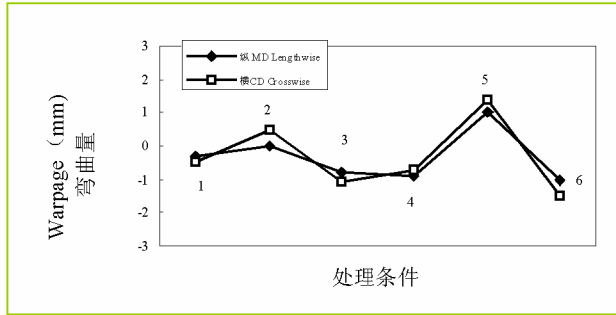
Stand values according to JIS-C-6485 規格值參照 JIS-C-6485

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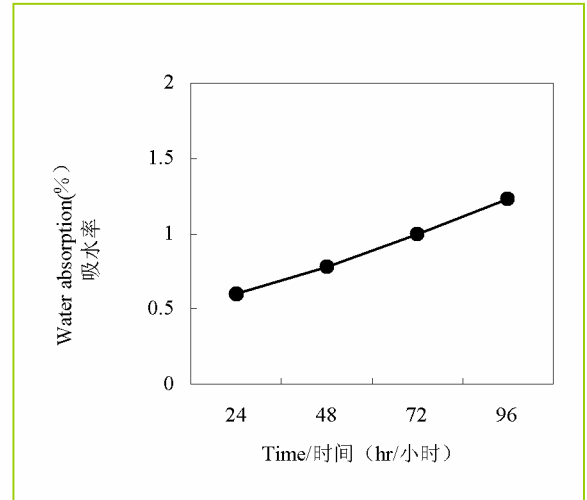
Speciality Chart 板材特性圖

Warpage of PCB during processing/印製電路板加工時彎曲度(Thickness 1.6mm single side)

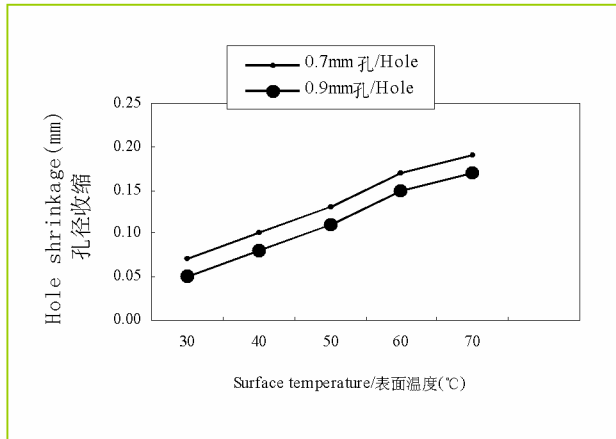


| | | |
|---|---|---|
| 1.Feeding 投料 | 2.Heating at 130°C for 90 sec 130°C下加熱90秒 | 3.Etching. Rinsing.Drying 蝕刻,清洗,烘乾 |
| 4.Heating at 200°C for 30 sec 200°C下加熱30秒 | 5.Punching at 50°C 50°C下沖孔 | 6.Soldering at 260 °C for 5sec 260°C 焊錫5秒 |

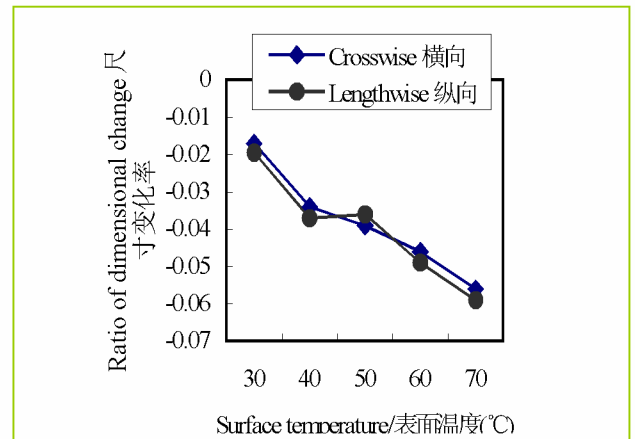
Water absorption 吸水率



Punched hole shrinkage
沖孔後孔徑收縮



Dimensional change of punched PCB
沖孔後之尺寸變化



Purchasing Information / 採購資訊

| Type 類型 | Thickness 厚度 | Copper Cladding 銅箔厚度 | Regular Size (mm) 常規尺寸 | CTI Value CTI 值 |
|-----------------|------------------|-------------------------|--|--------------------|
| KB-3152 FR-1 | 0.8mm ~ 1.6mm | 18µm 35µm 70µm | 1020*1220mm (40" *48") 1020*1020mm (40" *40") | 200V / 600V |

Note: Other sheet size and thickness could be available upon request.
可根據客戶要求提供其他尺寸和厚度。